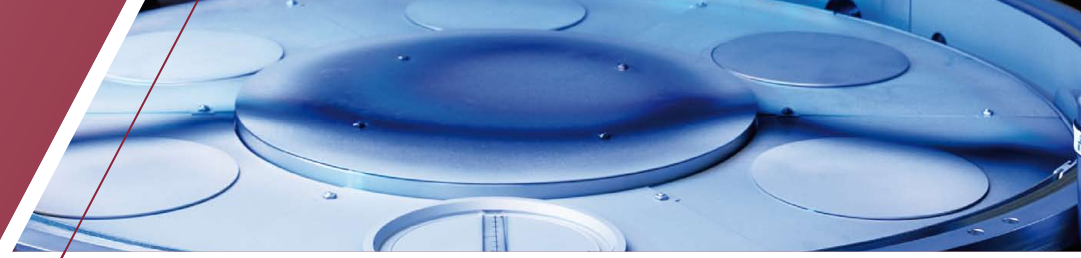


Cluster Type Equipment



FHR equips customers around the world with tailor-made thin-film equipment.

Cluster Type Equipment

Modular systems for advanced wafer processing

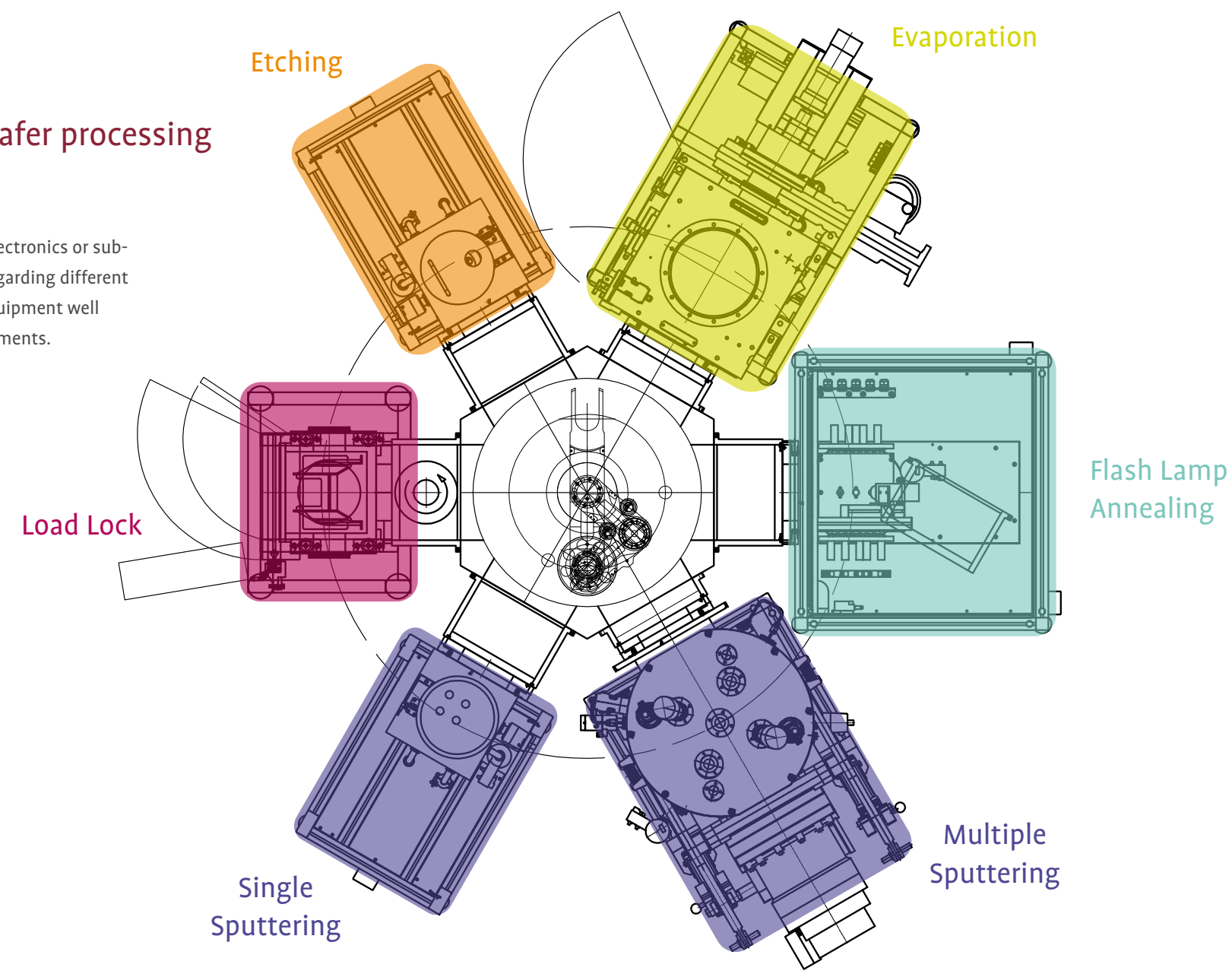
Cluster type tools are the standard for wafer-based microelectronics or substrates similar to wafers. However, their special flexibility regarding different processes and substrate handling make our cluster type equipment well suited for advanced R&D in scientific and industrial environments.

Various thin-film processing modules available

- ▲ Etching
- ▲ Sputtering
- ▲ Evaporation
- ▲ Plasma-enhanced CVD
- ▲ Atomic Layer Deposition
- ▲ Flash Lamp Annealing
- ▲ Rapid Thermal Processing

Modular concept for tailored and customized equipment

- ▲ Substrate sizes from 2 inch up to 300 mm diameter
- ▲ Substrate materials: metals, synthetics, glass
- ▲ Integrated PLC technology
- ▲ Handling of „extreme heavy“ substrates



Applications

Versatile function layers

- ▲ Conductive Layers
- ▲ Insulating Layers
- ▲ Barrier Layers
- ▲ Adhesion Layers
- ▲ Optical Layers

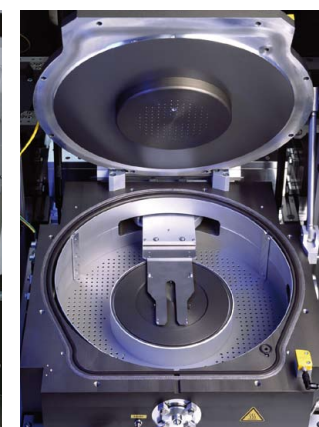
Versatile applications

- ▲ Semiconductors
- ▲ MEMS & Sensors
- ▲ Microelectronics
- ▲ Optoelectronics
- ▲ Optics
- ▲ Solar cells

Load lock module



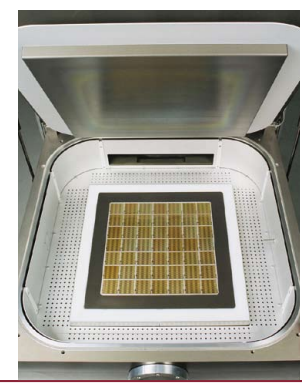
Etching module



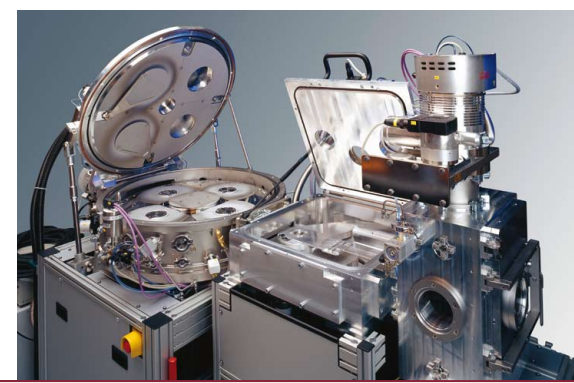
FHR RIE 150 x 4



Etching module



FHR MS 100 x 4



FHR MS 150 x 6





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Sometimes we have to tread pioneer paths to engineer and manufacture tailor-made solutions for customers' individual needs. Please contact us for additional information and to discuss your need.